	Т	

### Features

- High isolation 5000 VRMS
- Supports 0.3 A, 0.6 A, 0.9 A and 1.2 A
- RoHS compliant
- REACH compliance
- External creepage > 7.5mm
- Internal creepage > 6.0mm
- Insulation distance > 0.4mm
- Regulatory Approvals
  - UL UL1577 (pending approval)
  - VDE EN60747-5-5(VDE0884-5)
  - CQC GB4943.1, GB8898
  - IEC60065, IEC60950

### Description

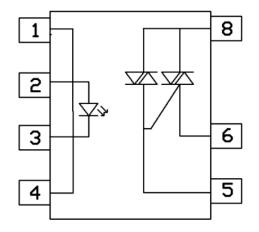
The random phase power Triac consists of a Triac and a photo-Triac, which is optically coupled to a gallium arsenide Infrared emitting diode, and house in a 7-lead DIP package. It also comes with different lead forming options.

## **Applications**

- Home appliances
- Industrial equipment



## Schematic



Note: Different bending options available. See package

dimension.



## Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
Viso	Isolation voltage		5000	Vrms	
TOPR	Operating temp	perature	-40 ~+85	°C	
T <sub>STG</sub>	Storage tempe	erature	-40 ~+125	°C	
Ŧ	Soldering temp	perature	260	°C	
T <sub>SOL</sub> ──	Wave soldering te	mperature	260	°C	
Emitter				·	
lF	LED forward o	current	50	mA	
VR	LED reverse v	voltage	6	V	
IFP	Peak forward	current	1	A	
Pin	Power dissipation		75	mW	
Detector			·	·	
Vdrm	Repetitive peak OFF	-state voltage	600	V	
		CTT0223	0.3		
		CTT1223	0.6		
It(RMS)	Continuous Current Load	CTT2223	0.9	— A	
		CTT3223	1.2		
		CTT0223	3		
		CTT1223	6	Α	
Ітѕм	Peak Current Load	CTT2223	9		
	CTT3223		12		
Pout	Power dissip	pation	800	mW	
Рт	Total power dissipation		850	mW	



### **Electrical Characteristics** *T<sub>A</sub>* = 25°C (unless otherwise specified)

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I⊧=10mA	-	-	1.3	V	
I <sub>R</sub>	Reverse Current	$V_R = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

#### **Detector Characteristics**

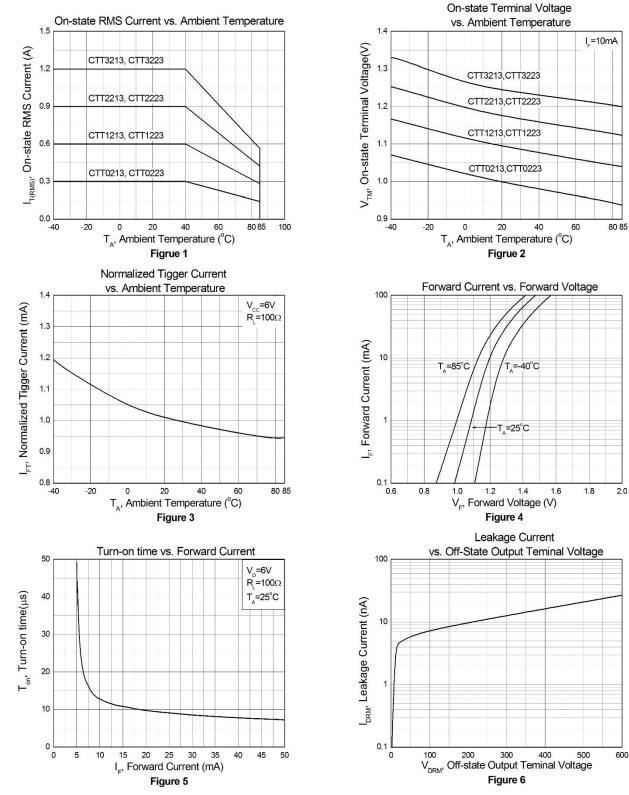
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Idrm	Peak Blocking Current	IF= 0mA, VDRM= Rated VDRM	-	-	100	uA	
Vinh	Inhibit Voltage	IF= Rated IFT	-	-	50	V	
V <sub>TM</sub>	Peak On-State Voltage	I <sub>F</sub> = Rated I <sub>FT</sub> , I <sub>TM</sub> = 100mA	-	-	2.5	V	
-1 / -14	Critical Rate of Rise off-State		000				
dv/dt	Voltage	VPEAK= Rated VDRM	200	-	-	V/µs	

#### **Transfer Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
IFT	Input Trigger Current	Terminal Voltage = 3V	-	-	10	mA	
IH	Holding Current		-	-	25	mA	
Rio	Isolation Resistance	VIO= 500VDC	1x10 <sup>11</sup>	-	-	Ω	
Сю	Isolation Capacitance	f= 1MHz	-	0.25	-	pF	



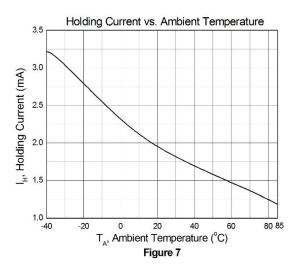
## **Typical Characteristic Curves**

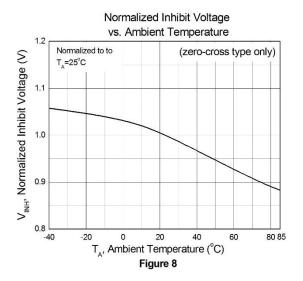


2.0

600



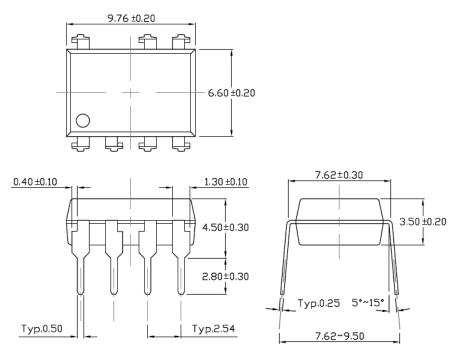




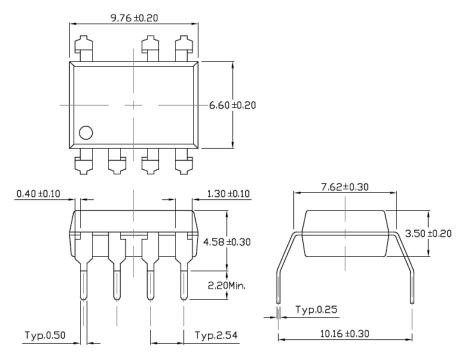


#### Package Dimension Dimensions in mm unless otherwise stated

### Standard DIP – Through Hole

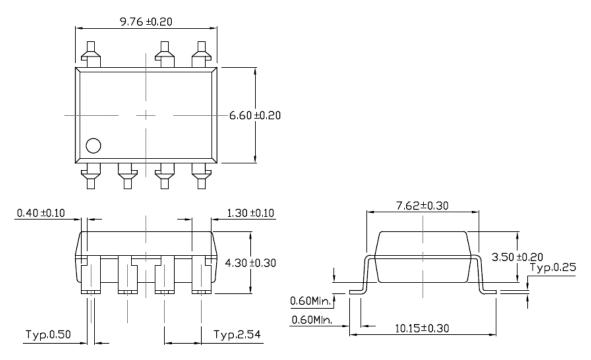


Gullwing (400mil) Lead Forming – Through Hole (M Type)

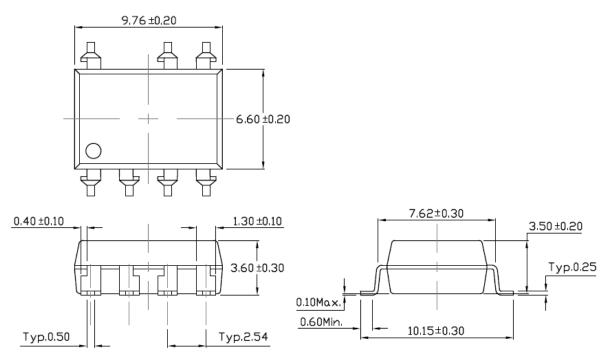




### Surface Mount Lead Forming (S Type)

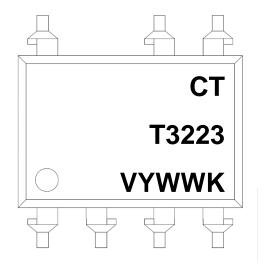


### Surface Mount (Low Profile) Lead Forming (SL Type)





## **Device Marking**



Note:	
СТ	: Denotes "CT Micro"
T3223	: Product Number
V	: VDE Safety Mark (option)
Y	: Fiscal Year
WW	: Work Week
K	: Production Code

## **Ordering Information**

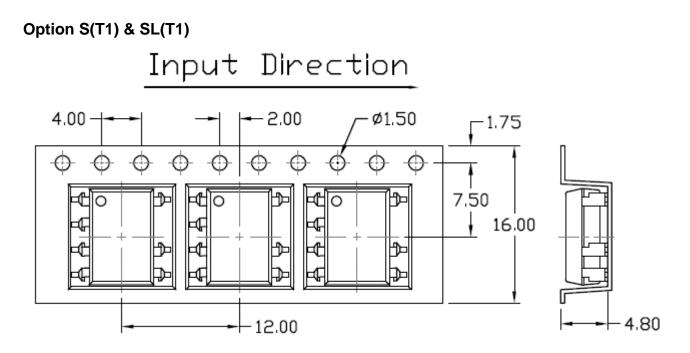
## CTTX223(V)(Y)(Z)

СТ	= Denotes "CT Micro"
TX223	= Product Number (Current Rating Option X=0, 1, 2, or 3)
V	= VDE safety mark option (V, or none)
Y	= Lead form option (S, SL, M or none)
Z	= Tape and reel option (T1, T2 or none)

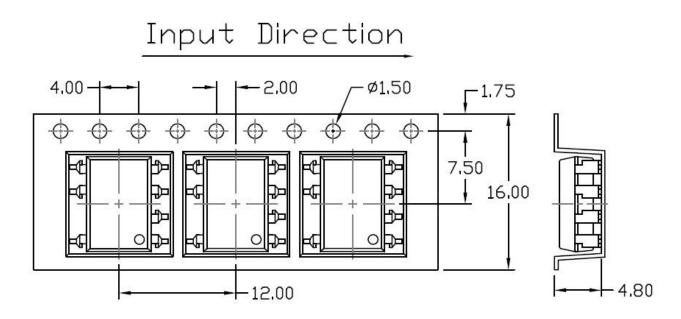
Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
М	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming- With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping 1000 Units/Red	



Carrier Tape Specifications Dimensions in mm unless otherwise stated



### Option S(T2) & SL(T2)





## Wave soldering (JEDEC22A111 compliant)

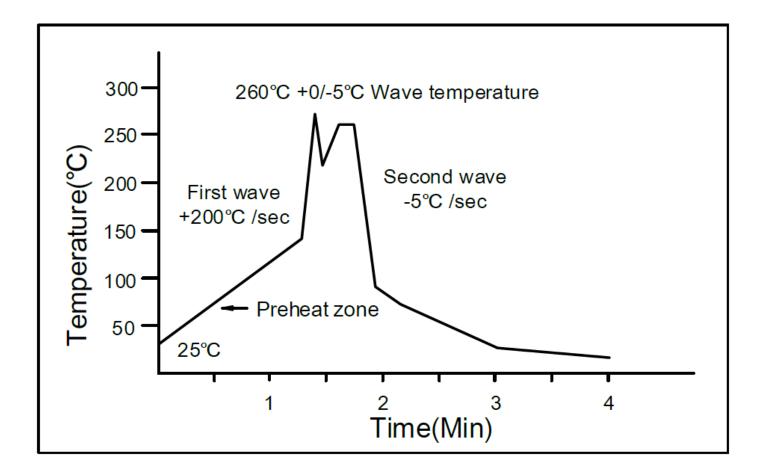
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



## Hand soldering by soldering iron

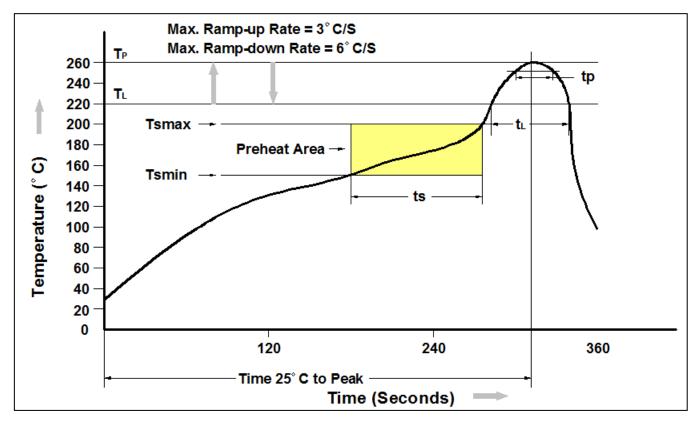
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+0/-5°C

Time: 3 sec max.



### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile	
Temperature Min. (Tsmin)	150°C	
Temperature Max. (Tsmax)	200°C	
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	
Ramp-up Rate (t∟ to tթ)	3°C/second max.	
Liquidous Temperature (T <sub>L</sub> )	217°C	
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds	
Peak Body Package Temperature	260°C +0°C / -5°C	
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds	
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max	
Time 25°C to Peak Temperature	8 minutes max.	



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